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Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

Cypress Semiconductor Package Qualification Report

**QTP# 042902 VERSION*A
September 2014**

**48-Lead TSOP I & 54-Lead TSOP II
MSL3, Pb-Free, 260C Reflow
ASEK-Taiwan (G)**

**FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PRODUCT QUALIFICATION HISTORY

Qual Report	Description of Qualification Purpose	Date
042902	48-Lead TSOP I & 54-Lead TSOP II, Pb-Free, MSL3, 260C Reflow using Cel 9200HF, 8340 Epoxy and 100% Tin (Sn) with Annealing Process (150C, 1 hour) assembled in ASEK- Taiwan	Jan 05

Major Package Information Used in this Qualification	
Package Designation:	ZW54
Package Outline, Type, or Name:	54-Lead Thin Small Outline Package (TSOP II)
Mold Compound Name/Manufacturer:	CEL9200HF
Mold Compound Flammability Rating:	V-O per UL 94
Oxygen Rating Index:	N/A
Lead Frame Material:	Copper
Lead Finish, Composition / Thickness:	100% Sn
Die Backside Preparation Method/Metallization:	Grinding
Die Separation Method:	Sawing
Die Attach Supplier:	Ablestik
Die Attach Material:	8340A
Bond Diagram Designation	10-06018
Wire Bond Method:	Thermosonic
Wire Material/Size:	1.0mil
Thermal Resistance Theta JA °C/W:	57.12° C/W
Package Cross Section Yes/No:	Yes
Assembly Process Flow:	49-41999M
Name/Location of Assembly (prime) facility:	ASEK-Taiwan (G)

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	CML-R
Fault Coverage:	100%

Note: Please contact a Cypress Representative for other packages availability.

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Acoustic Microscopy Test (C-SAM)	J-STD-020	P
Adhesion of Lead Finish	MIL-STD-883, Method 2025	P
External Visual	MIL-PRF-38535, MILSTD-883, METHOD 2009,	P
High Accelerated Saturation Test (HAST)	130C, 85%RH, 3.63V Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30C/60% RH+3IR-Reflow, 260°C+0, -5°C	P
Pressure Cooker Test	No bias, 121°C, 100% RH, 15 PSIG Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30°C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
Temperature Cycle	MIL-STD-883C, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30°C/60% RH+3IR-Reflow, 260°C+0, -5°C	P

Reliability Test Data

QTP #:042902

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: ACOUSTIC, MSL3							
CY7C1069AV33 (7C1069A)	4414223	610432942	TAIWAN-G	COMP	15	0	
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	COMP	15	0	
STRESS: ADHESION OF LEAD FINISH							
CY7C1069AV33 (7C1069A)	4414223	610432942	TAIWAN-G	COMP	3	0	
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	COMP	3	0	
STRESS: EXTERNAL VISUAL							
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	COMP	15	0	
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 3.63V)PRE COND 192 HR 30C/60%RH, MSL3							
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	128	50	0	
STRESS: PRESSURE COOKER TEST, 121C, 100%RH,, PRE COND 192 HR 30C/60%RH, MSL3							
CY7C1069AV33 (7C1069A)	4414223	610432942	TAIWAN-G	168	50	0	
STRESS: TC CONDITION C, -65C TO 150C, PRE COND. 192 HRS 30C/60% RH, MSL3							
CY7C1069AV33 (7C1069A)	4414223	610432942	TAIWAN-G	300	48	0	
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	300	49	0	
CY7C1069AV33 (7C1069A)	4414223	610432943	TAIWAN-G	500	48	0	

Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	4141014	HSTO	Initial Spec Release Initiate report as per memo LGQ-487.
*A	4517626	HSTO	Align qualification report based on the new template in the front page

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